XILINX

PK816(v1.1) January 24, 2020

100% Material Declaration Data Sheet for 7-Series SBG484 RoHS 6/6

Average Weight : 1.4867 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					**0.237468**	**15.973%**
	Silicon	7440-21-3	100.00	basis	0.237468	
Bump					**0.009525**	**0.641%**
	Tin	7440-31-5	98.20	basis	0.009354	
	Silver	7440-22-4	1.80	basis	0.000171	
Underfill					**0.034000**	**2.287%**
	Bisphenol F type liquid epoxy	9003-36-5	15.00	basis	0.005100	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.003400	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001700	
	Amine type hardener	trade secret	10.00	basis	0.003400	
	Silicon dioxide	60676-86-0	58.00	filler	0.019720	
	Carbon black	1333-86-4	1.00	color agent	0.000340	
	Additives	trade secret	1.00	additives	0.000340	
Solder ball					**0.233980**	**15.738%**
	Tin	7440-31-5	96.50	Main material	0.225791	
	Silver	7440-22-4	3.00	Main material	0.007019	
	Copper	7440-50-8	0.50	Main material	0.001170	
Substrate					**0.971727**	**65.361%**
	Copper	7440-50-8	36.38		0.353520	
	Tin	7440-31-5	0.79		0.007677	
	Silver	7440-22-4	0.02		0.000194	
	Core	N/A	46.77		0.454477	
	ABF	N/A	13.8		0.134098	
	Solder Mask	N/A	2.24		0.021761	

Revision History

Date	Version	Description of Revisions
11/8/2016	1.0	Initial Xilinx release.
1/24/2020	1.1	Updated Title

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